

Title (en)
ELECTRONIC MODULE FOR CHIP CARD

Title (de)
ELEKTRONISCHES MODUL FÜR EINE CHIPKARTE

Title (fr)
MODULE ELECTRONIQUE POUR CARTE A PUCE

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Application
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Abstract (en)
[origin: FR2761498A1] The invention concerns an electronic module, in particular designed to be fixed in an electronic device in the form of a card, comprising a medium (40) including at least a surface (44) provided with contact pads (46; 48; 50) and a microcircuit (56) which is fixed on said medium (40) and which comprises exit hubs (60, 62) each connected to a medium contact pad. The invention is characterised in that the connections (66, 68) between the exit hubs and the contact pads consist of a cord made of an adhesive conductive substance matching the relief of the medium. Advantageously, the conductive substance is a conductive isotropic adhesive.

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IPC 8 full level
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